

MC74LCX139

Dual Low-Voltage CMOS 2-to-4 Decoder/Demultiplexer

With 5V-Tolerant Inputs

The MC74LCX139 is a high performance, 2-to-4 decoder/demultiplexer operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5 V allows MC74LCX139 inputs to be safely driven from 5 V devices. The MC74LCX139 is suitable for memory address decoding and other TTL level bus oriented applications.

The MC74LCX139 high-speed 2-to-4 decoder/demultiplexer accepts two binary weighted inputs (A0, A1) and, when enabled, provides four mutually exclusive active-LOW outputs. The LCX139 features an active low Enable input. All outputs will be HIGH unless En is LOW. The LCX139 can be used as an 8-output demultiplexer by using one of the active-LOW Enable inputs as the data input and the other Enable input as a strobe. The Enable inputs which are not used must be permanently tied to ground.

Current drive capability is 24 mA at the outputs.

Features

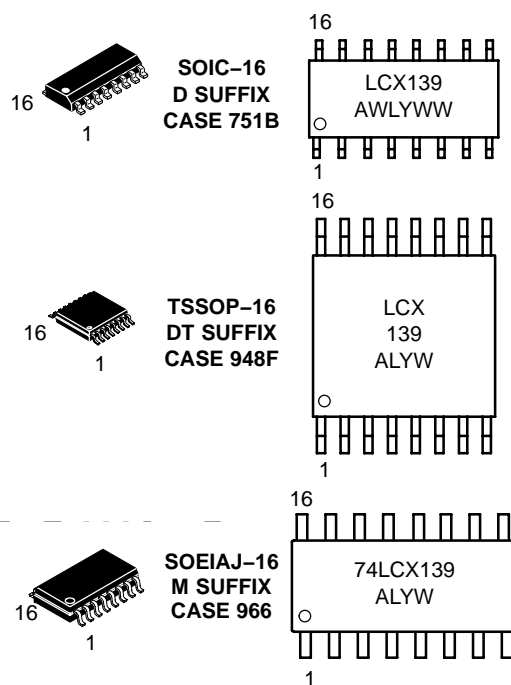
- Designed for 2.3 to 3.6 V V_{CC} Operation
- 5 V Tolerant Inputs – Interface Capability With 5 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 μ A) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V
Machine Model >200 V
- Pb-Free Packages are Available*



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<http://onsemi.com>

MARKING DIAGRAMS



A = Assembly Location
L, WL = Wafer Lot
Y = Year
W, WW = Work Week

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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Figure 1. Pin Assignment

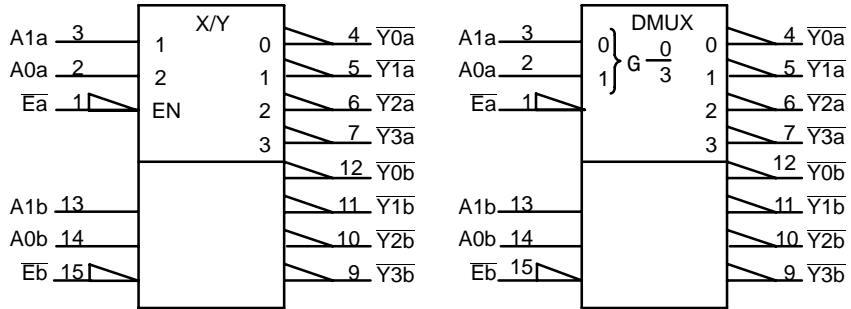


Figure 2. IEC Logic Diagram

PIN NAMES

Pins	Function
A0n–A1n	Address Inputs
En	Enable Inputs
Y0n–Y3n	Outputs

TRUTH TABLE

Inputs			Outputs			
\bar{E}	A1	A0	Y0	Y1	Y2	Y3
H	X	X	H	H	H	H
L	L	L	L	H	H	H
L	L	H	H	L	H	H
L	H	L	H	H	L	H
L	H	H	H	H	H	L

H = High Voltage Level;
L = Low Voltage Level;
Z = High Impedance State

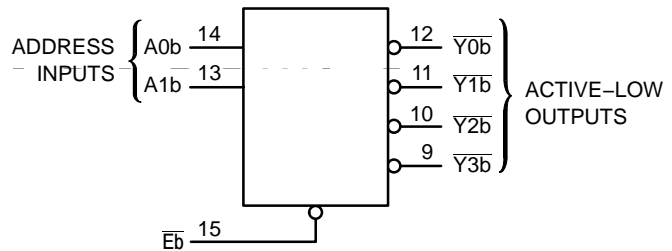
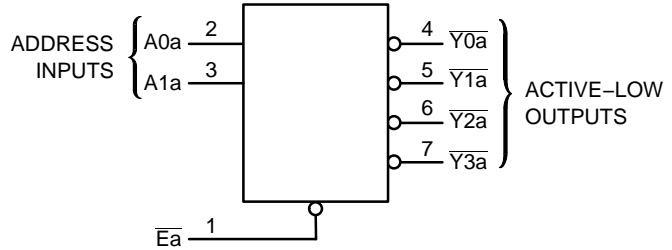


Figure 3. Logic Diagram

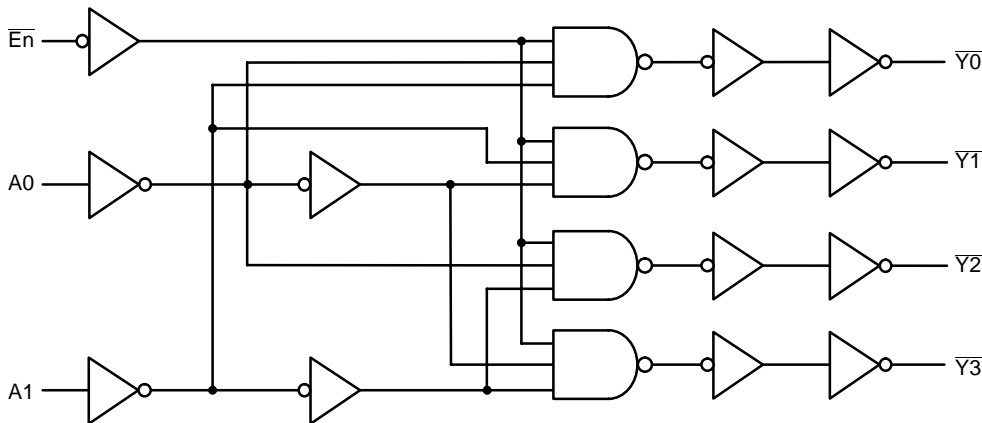


Figure 4. Expanded Logic Diagram
(1/2 of Device)

MC74LCX139

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0		V
V _I	DC Input Voltage	-0.5 ≤ V _I ≤ +7.0		V
V _O	DC Output Voltage	-0.5 ≤ V _O ≤ V _{CC} + 0.5	Output in HIGH or LOW State. (Note 1)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
I _O	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. I_O absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Typ	Max	Unit	
V _{CC}	Supply Voltage	Operating	2.0	2.3 to 3.3	3.6	V
		Data Retention Only	1.5		3.6	
V _I	Input Voltage	0		5.5	V	
V _O	Output Voltage (HIGH or LOW State)	0		V _{CC}	V	
I _{OH}	HIGH Level Output Current	V _{CC} = 3.0 V – 3.6 V		-24	mA	
		V _{CC} = 2.7 V – 3.0 V		-12		
		V _{CC} = 2.3 V – 2.7 V		-8		
I _{OL}	LOW Level Output Current	V _{CC} = 3.0 V – 3.6 V		+24	mA	
		V _{CC} = 2.7 V – 3.0 V		+12		
		V _{CC} = 2.3 V – 2.7 V		+8		
T _A	Operating Free-Air Temperature	-40		+85	°C	
Δt/ΔV	Input Transition Rise or Fall Rate, V _{IN} from 0.8 V to 2.0 V, V _{CC} = 3.0 V	0		10	ns/V	

ORDERING INFORMATION

Device	Package	Shipping [†]
MC74LCX139D	SOIC-16	48 Units / Rail
MC74LCX139DR2	SOIC-16	2500 Tape & Reel
MC74LCX139DR2G	SOIC-16 (Pb-Free)	2500 Tape & Reel
MC74LCX139DT	TSSOP-16*	96 Units / Rail
MC74LCX139DTR2	TSSOP-16*	2500 Tape & Reel
MC74LCX139M	SOEIAJ-16	48 Units / Rail
MC74LCX139MEL	SOEIAJ-16	2000 Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

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DC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic	Condition	T _A = -40°C to +85°C		Unit
			Min	Max	
V _{IH}	HIGH Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V	1.7		V
		2.7 V ≤ V _{CC} ≤ 3.6 V	2.0		
V _{IL}	LOW Level Input Voltage (Note 2)	2.3 V ≤ V _{CC} ≤ 2.7 V		0.7	V
		2.7 V ≤ V _{CC} ≤ 3.6 V		0.8	
V _{OH}	HIGH Level Output Voltage	2.3 V ≤ V _{CC} ≤ 3.6 V; I _{OL} = 100 μA	V _{CC} - 0.2		V
		V _{CC} = 2.3 V; I _{OH} = -8 mA	1.7		
		V _{CC} = 2.7 V; I _{OH} = -12 mA	2.2		
		V _{CC} = 3.0 V; I _{OH} = -18 mA	2.4		
		V _{CC} = 3.0 V; I _{OH} = -24 mA	2.2		
V _{OL}	LOW Level Output Voltage	2.3 V ≤ V _{CC} ≤ 3.6 V; I _{OL} = 100 μA		0.2	V
		V _{CC} = 2.3 V; I _{OL} = 8 mA		0.7	
		V _{CC} = 2.7 V; I _{OL} = 12 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 16 mA		0.4	
		V _{CC} = 3.0 V; I _{OL} = 24 mA		0.55	
I _I	Input Leakage Current	2.3 V ≤ V _{CC} ≤ 3.6 V; 0 V ≤ V _I ≤ 5.5 V		±5	μA
I _{CC}	Quiescent Supply Current	2.3 ≤ V _{CC} ≤ 3.6 V; V _I = GND or V _{CC}		10	μA
		2.3 ≤ V _{CC} ≤ 3.6 V; 3.6 ≤ V _I or V _O ≤ 5.5 V		±10	
ΔI _{CC}	Increase in I _{CC} per Input	2.3 ≤ V _{CC} ≤ 3.6 V; V _{IH} = V _{CC} - 0.6 V		500	μA

2. These values of V_I are used to test DC electrical characteristics only.

AC CHARACTERISTICS t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

Symbol	Parameter	Limits						Unit
		T _A = -40°C to +85°C						
		V _{CC} = 3.0 V to 3.6 V		V _{CC} = 2.7 V		V _{CC} = 2.3 V to 2.7 V		
		C _L = 50 pF		C _L = 50 pF		C _L = 30 pF		
		Min	Max	Min	Max	Min	Max	
t _{PLH}	Propagation Delay	0.8	6.2	1.0	7.3	0.8	9.3	ns
t _{PHL}	A to Y	0.8	6.2	1.0	7.3	0.8	9.3	
t _{PLH}	Propagation Delay	0.8	4.7	1.0	5.2	0.8	7.2	ns
t _{PHL}	E to Y	0.8	4.7	1.0	5.2	0.8	7.2	
t _{OSSL}	Output-to-Output Skew (Note 3)		1.0					ns
t _{OSLH}			1.0					ns

3. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSSL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	7	pF
C _{OUT}	Output Capacitance	V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	10MHz, V _{CC} = 3.3 V, V _I = 0 V or V _{CC}	25	pF

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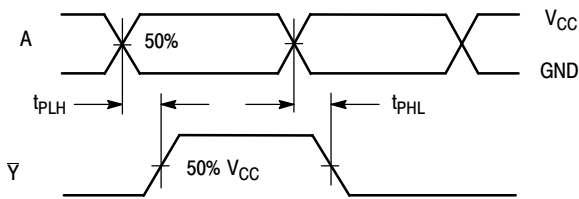


Figure 5. Waveform 1 Prop Delays

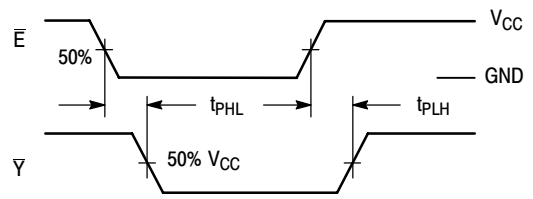
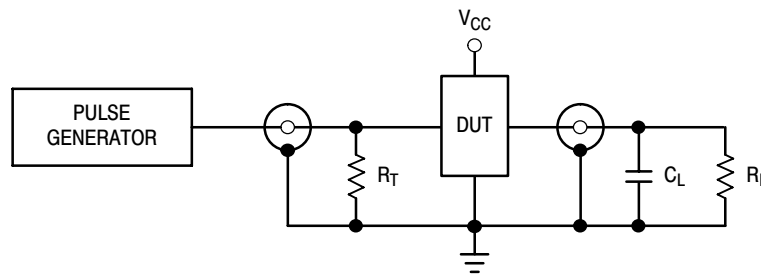


Figure 6. Waveform 2 Output Enable



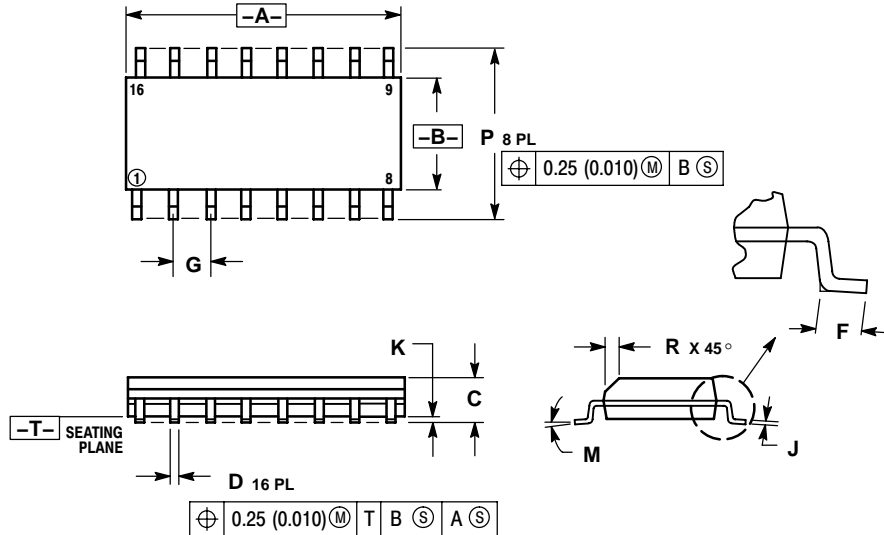
$C_L = 50 \text{ pF}$ or equivalent (Includes jig and probe capacitance)
 $R_L = R_1 = 500 \ \Omega$ or equivalent
 $R_T = Z_{OUT}$ of pulse generator (typically $50 \ \Omega$)

Figure 7. Test Circuit

MC74LCX139

PACKAGE DIMENSIONS

SOIC-16
D SUFFIX
CASE 751B-05
ISSUE J

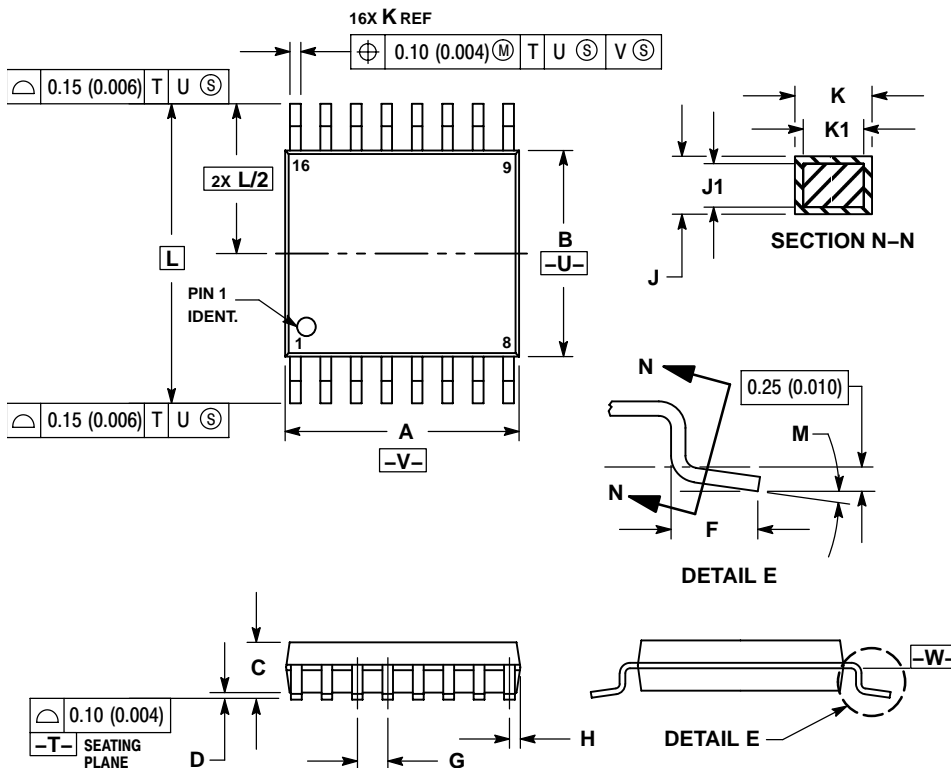


NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	9.80	10.00	0.386	0.393
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.054	0.068
D	0.35	0.49	0.014	0.019
F	0.40	1.25	0.016	0.049
G	1.27 BSC		0.050 BSC	
J	0.19	0.25	0.008	0.009
K	0.10	0.25	0.004	0.009
M	0°	7°	0°	7°
P	5.80	6.20	0.229	0.244
R	0.25	0.50	0.010	0.019

TSSOP-16
DT SUFFIX
CASE 948F-01
ISSUE O



NOTES:

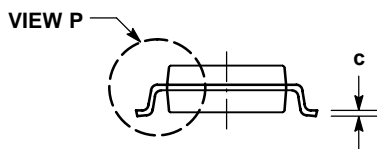
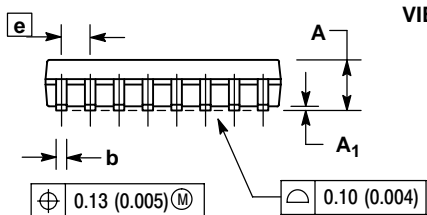
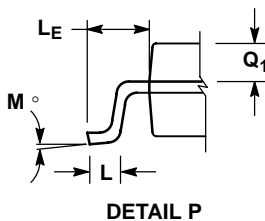
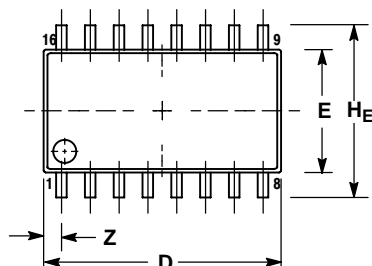
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.90	5.10	0.193	0.200
B	4.30	4.50	0.169	0.177
C	---	1.20	---	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
H	0.18	0.28	0.007	0.011
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0°	8°	0°	8°

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PACKAGE DIMENSIONS

SOEIAJ-16
M SUFFIX
CASE 966-01
ISSUE O



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	---	2.05	---	0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
c	0.18	0.27	0.007	0.011
D	9.90	10.50	0.390	0.413
E	5.10	5.45	0.201	0.215
e	1.27 BSC		0.050 BSC	
H _E	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
L _E	1.10	1.50	0.043	0.059
M	0° 10°		0° 10°	
Q ₁	0.70	0.90	0.028	0.035
Z	---	0.78	---	0.031

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